



**RAYSTAR**

# 曜凌光電股份有限公司

住址: 42878 台中市大雅区科雅路 25 號 5F WEB: <http://www.Raystar-Optronics.com>  
5F., No.25, Keya Rd., Daya Dist., Taichung E-mail: sales@raystar-optronics.com  
City 428, Taiwan Tel:886-4-2565-0761 Fax : 886-4-2565-0760

## RG12864A-YHY-V

---

### SPECIFICATION

CUSTOMER:

APPROVED BY	
PCB VERSION	
DATE	

FOR CUSTOMER USE ONLY

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY

ISSUED DATE:

# Contents

	Page
1. Revision History	3
2. General Specification	4
3. Module Coding System	5
4. Interface Pin Function	6
5. Outline dimension & Block Diagram	7
6. Display Control Instruction	8
7. Timing Characteristics	11
8. Optical Characteristics	12
9. Absolute Maximum Ratings	13
10. Electrical Characteristics	13
11. Backlight Information	14
12. Reliability	15
13. Inspection specification	16
14. Precautions in use of LCD Modules	20
15. Material List of Components for RoHs	21
16. Recommendable storage	21

## 1. Revision History

DATE	VERSION	REVISED PAGE NO.	Note
2012-11-27	1		First issue

## 2. General Specification

The Features is described as follow:

- Module dimension: 93.0 x 70.0 x 13.6 (max.) mm<sup>3</sup>
- View area: 72.0 x 40.0 mm<sup>2</sup>
- Active area: 66.52 x 33.24 mm<sup>2</sup>
- Number of dots: 128 x 64
- Dot size: 0.48 x 0.48 mm<sup>2</sup>
- Dot pitch: 0.52 x 0.52 mm<sup>2</sup>
- LCD type: STN Positive, Yellow Green Transflective
- Duty: 1/64
- View direction: 6 o'clock
- Backlight Type: LED, Yellow Green

### 3. Module Coding System

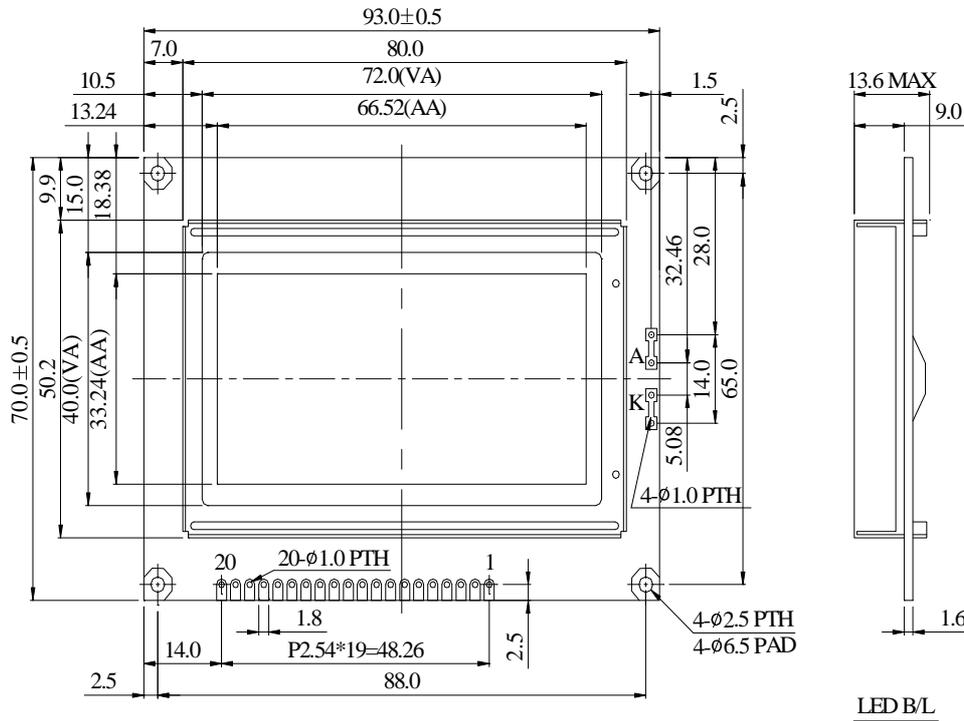
<b>R</b>	<b>G</b>	<b>12864</b>	<b>A</b>	<b>-</b>	<b>Y</b>	<b>H</b>	<b>Y</b>	<b>-</b>	<b>V</b>
1	2	3	4	-	5	6	7	-	8

Item	Description		
1	<b>R : Raystar Optronics Inc.</b>		
2	Display	C : Character Type,	
		<b>G : Graphic Type</b>	
3	Number of dots : <b>128 x64 Dots</b>		
4	Serials code		
5	LCD	P : TN Positive, Gray	
		N : TN Negative,	
		G : STN Positive, Gray	
		<b>Y : STN Positive, Yellow Green</b>	
		B : STN Negative, Blue	
		F : FSTN Positive	
6	Polarizer Type, Temperature range, View direction	A : Reflective, N.T, 6:00	K : Transflective, W.T,12:00
		D : Reflective, N.T, 12:00	1 : Transflective, U.T,6:00
		G : Reflective, W. T, 6:00	4 : Transflective, U.T.12:00
		J : Reflective, W. T, 12:00	C : Transmissive, N.T,6:00
		0 : Reflective, U. T, 6:00	F : Transmissive, N.T,12:00
		3 : Reflective, U. T, 12:00	I : Transmissive, W. T, 6:00
		B : Transflective, N.T,6:00	L : Transmissive, W.T,12:00
		E : Transflective, N.T.12:00	2 : Transmissive, U. T, 6:00
		<b>H:Transflective, W.T,6:00</b>	5 : Transmissive, U.T,12:00
7	Backlight	N : Without backlight	<b>Y : LED, Yellow Green</b>
		P : EL, Blue green	A : LED, Amber
		T : EL, Green	W : LED, White
		D : EL, White	O : LED, Orange
		F : CCFL, White	G : LED, Green
8	Special code	V: Build-in Negative Voltage	

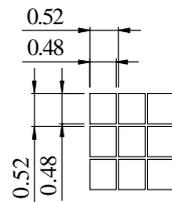
## 4. Interface Pin Function

Pin #	Symbol	Level	Description
1	V <sub>SS</sub>	0V	Ground
2	V <sub>DD</sub>	5.0V	Supply voltage for logic
3	V <sub>o</sub>	(Variable)	Operating voltage for LCD
4	D/I	H/L	H: Data , L : Instruction
5	R/W	H/L	H: Read (MPU←Module) , L: Write (MPU→Module)
6	E	H	Enable signal
7	DB0	H/L	Data bus line
8	DB1	H/L	Data bus line
9	DB2	H/L	Data bus line
10	DB3	H/L	Data bus line
11	DB4	H/L	Data bus line
12	DB5	H/L	Data bus line
13	DB6	H/L	Data bus line
14	DB7	H/L	Data bus line
15	CS1	H	Select Column 1~ Column 64
16	CS2	H	Select Column 65~ Column 128
17	RES	L	Reset signal
18	V <sub>out</sub>	—	Negative Voltage Output
19	A	—	Power Supply for LED backlight ( + )
20	K	—	Power Supply for LED backlight ( - )

## 5. Outline Dimension & Block Diagram

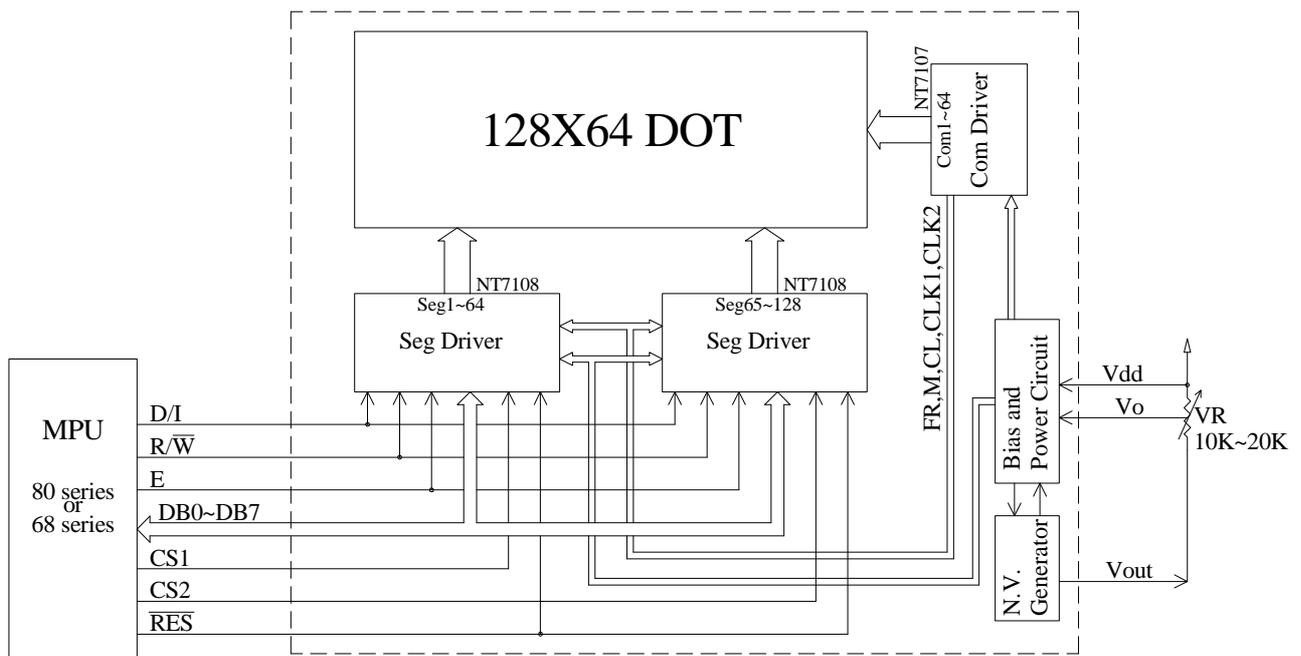


PIN NO.	SYMBOL
1	Vss
2	Vdd
3	Vo
4	D/I
5	R/W
6	E
7	DB0
8	DB1
9	DB2
10	DB3
11	DB4
12	DB5
13	DB6
14	DB7
15	CS1
16	CS2
17	RES
18	Vout
19	A
20	K



DOT SIZE

The non-specified tolerance of dimension is  $\pm 0.3\text{mm}$ .



External contrast adjustment.

## 6. Display Control Instruction

The internal state of NT7108 is defined by Display Control Instruction, sent by MPU, shown in the table below.

Instruction	RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	Function	
Display on/off	L	L	L	L	H	H	H	H	H	L/H	Controls the display on or off. Internal status and display RAM data is not affected. L:OFF, H:ON	
Set address (Y address)	L	L	L	H	Y address (0-63)						Sets the Y address in the Y address counter.	
Set page (X address)	L	L	H	L	H	H	H	Page (0-7)			Sets the X address at the X address register.	
Display Start line (Z address)	L	L	H	H	Display start line (0-63)						Indicates the display data RAM displayed at the top of the screen.	
Status read	L	H	Busy	L	On/Off	Reset	L	L	L	L	Read status. BUSY L: Ready H: In operation ON/OFF L: Display ON H: Display OFF RESET L: Normal H: Reset	
Write display data	H	L	Write data									Writes data (DB0: 7) into display data RAM. After writing instruction, Y address is increased by 1 automatically.
Read display data	H	H	Read data									Reads data (DB0: 7) from display data RAM to the data bus.

### Instruction

#### Display ON/OFF

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	0	1	1	1	1	1	D

**D** gives the value of DB0. The Display Data appears as **D** is 1, and disappears as **D** is 0. The Display Data still remains in Display Data RAM as **D** is 0, though the data is not shown on the screen. The Display Data can reappear by switching **D** from 0 to 1.

**SET ADDRESS (Y ADDRESS)**

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	1	AC5	AC4	AC3	AC2	AC1	AC0

The Y addresses (AC0-AC5) of Display Data RAM are set in the Y address counter. Each address is set by instruction and incremented by 1 automatically by read or write operations.

**SET PAGE (X ADDRESS)**

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	1	0	1	1	1	AC2	AC1	AC0

The X address (AC0-AC2) of Display Data RAM is set in the X address counter. Writing or reading to or from MPU is executed in this specified page until the next page is set.

**DISPLAY START LINE (Z ADDRESS)**

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	1	1	AC5	AC4	AC3	AC2	AC1	AC0

Z addresses (AC0-AC5) of the Display Data RAM are set in the display start line register and displayed at the top of the screen. When the display duty cycle is 1/64 or others (1/32-1/64), the data of total line number of LCD screen are displayed from the line specified by display start line instruction.

**STATUS READ**

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	1	BUSY	0	ON/OFF	RESET	0	0	0	0

- BUSY

As BUSY is 1, the Chip is executing internal operation and can not accept any instruction.

As BUSY is 0, the Chip is ready to accept any instruction.

- ON/OFF

As ON/OFF is 1, the display is OFF.

As ON/OFF is 0, the display is ON.

- RESET

When RESET is 1, the system is being initialized.

In this condition, no instructions can be accepted except for the Status Read instruction.

As RESET is 0, initializing has finished and the system is in its normal operation condition.

**WRITE DISPLAY DATA**

<b>RS</b>	<b>R/W</b>	<b>DB7</b>	<b>DB6</b>	<b>DB5</b>	<b>DB4</b>	<b>DB3</b>	<b>DB2</b>	<b>DB1</b>	<b>DB0</b>
1	0	D7	D6	D5	D4	D3	D2	D1	D0

The Write Display Data (D0-D7) are written into the Display Data RAM. Completing the writing instruction, Y address is increased by 1 automatically.

**READ DISPLAY DATA**

<b>RS</b>	<b>R/W</b>	<b>DB7</b>	<b>DB6</b>	<b>DB5</b>	<b>DB4</b>	<b>DB3</b>	<b>DB2</b>	<b>DB1</b>	<b>DB0</b>
1	1	D7	D6	D5	D4	D3	D2	D1	D0

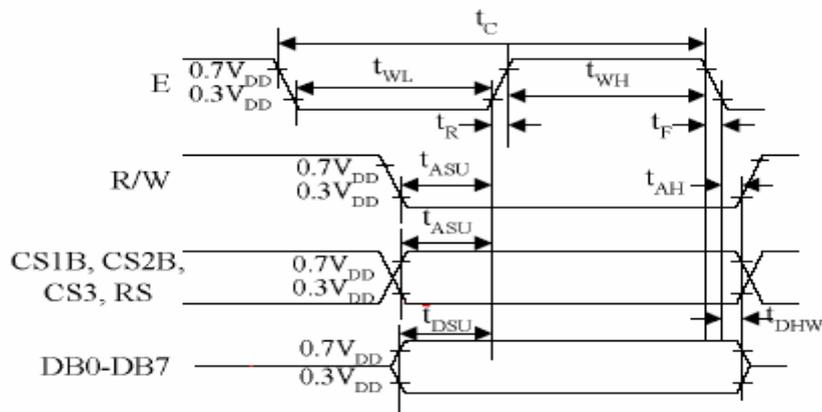
The Read Display Data (D0-D7) are read from the display data RAM. Completing the reading instruction, Y address is increased by 1 automatically.

## 7. Timing Characteristics

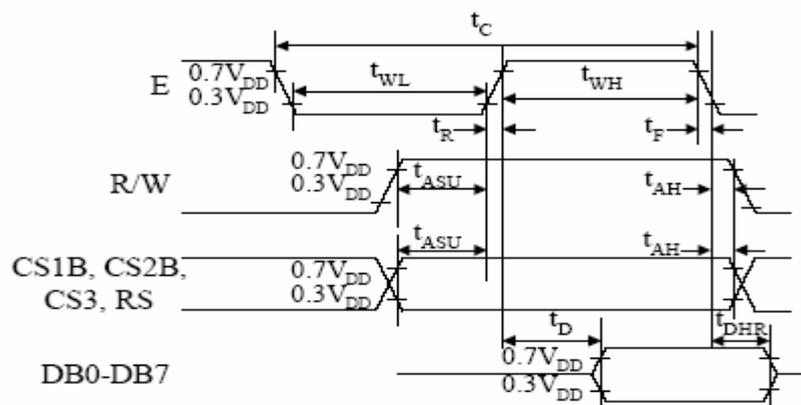
MPU Interface

(T=25°C, VDD=+5.0V±0.5)

Characteristic	Symbol	Min	Typ	Max	Unit
E cycle	tcyc	1000	—	—	ns
E high level width	twhE	450	—	—	ns
E low level width	twlE	450	—	—	ns
E rise time	tr	—	—	25	ns
E fall time	tf	—	—	25	ns
Address set-up time	tas	140	—	—	ns
Address hold time	tah	10	—	—	ns
Data set-up time	tdsw	140	—	—	ns
Data delay time	tddr	—	—	320	ns
Data hold time (write)	tdhw	10	—	—	ns
Data hold time (read)	tdhr	20	—	—	ns



MPU Write Timing

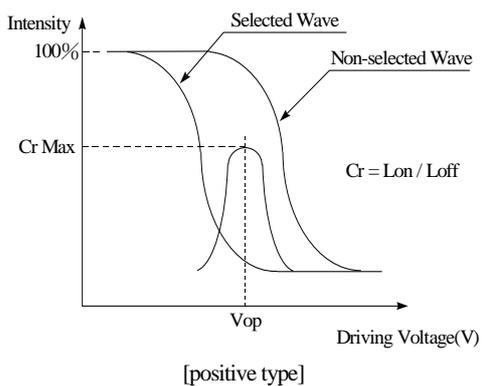


MPU Read Timing

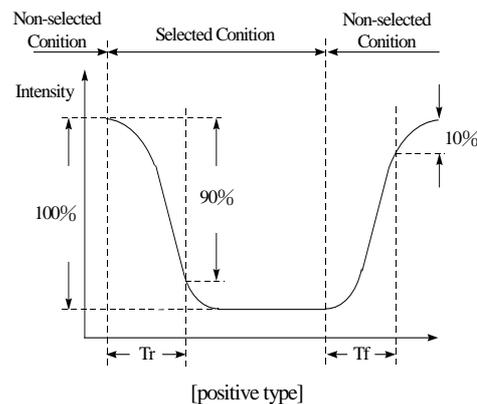
## 8. Optical Characteristics

Item	Symbol	Condition	Min	Typ	Max	Unit
View Angle	$(V)\theta$	$CR \geq 2$	20	—	40	deg
	$(H)\varphi$	$CR \geq 2$	-30	—	30	deg
Contrast Ratio	CR	—	—	3	—	—
Response Time	T rise	—	—	200	300	ms
	T fall	—	—	200	300	ms

### Definition of Operation Voltage, $V_{op}$ .



### Definition of Response Time, $T_r$ and $T_f$ .



#### Conditions:

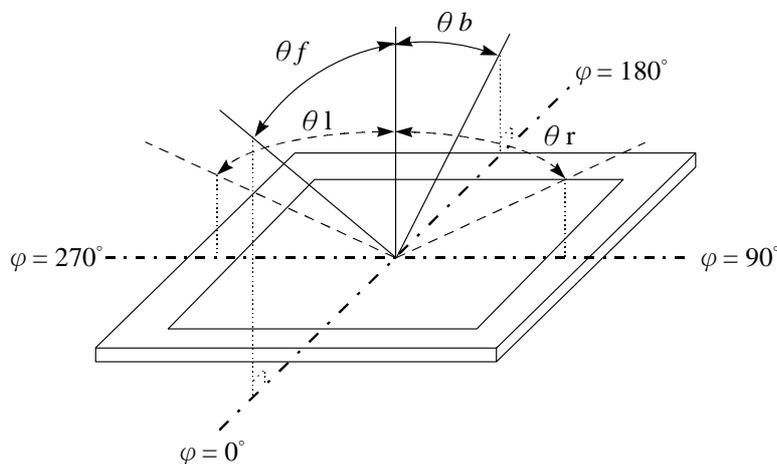
Operating Voltage :  $V_{op}$

Viewing Angle( $\theta$ ,  $\varphi$ ) :  $0^\circ$ ,  $0^\circ$

Frame Frequency: 64 HZ

Driving Waveform: 1/N duty, 1/a bias

### Definition of viewing angle ( $CR \geq 2$ )



## 9. Absolute Maximum Ratings

Item	Symbol	Min	Typ	Max	Unit
Operating Temperature	$T_{OP}$	-20	—	+70	°C
Storage Temperature	$T_{ST}$	-30	—	+80	°C
Input Voltage	$V_I$	0	—	$V_{DD}$	V
Supply Voltage For Logic	$V_{DD}$	0	—	6.7	V
Supply Voltage For LCD	$V_{DD}-V_{LCD}$	0	—	16.7	V
Supply Voltage For LCD	$V_{DD}-V_{OUT}$	—	—	-10	V

## 10. Electrical Characteristics

Item	Symbol	Condition	Min	Typ	Max	Unit
Supply Voltage For Logic	$V_{DD}-V_{SS}$	—	4.5	5.0	5.5	V
Supply Voltage For LCD	$V_{DD}-V_0$	$T_a=-20^{\circ}\text{C}$	—	—	10.6	V
		$T_a=25^{\circ}\text{C}$	8.6	8.9	9.2	V
		$T_a=+70^{\circ}\text{C}$	7.6	—	—	V
Input High Volt.	$V_{IH}$	—	2.0	—	$V_{DD}$	V
Input Low Volt.	$V_{IL}$	—	0	—	0.8	V
Output High Volt.	$V_{OH}$	—	2.4	—	$V_{DD}$	V
Output Low Volt.	$V_{OL}$	—	—	—	0.4	V
Supply Current	$I_{DD}$	—	—	18	—	mA

## 11. Backlight Information

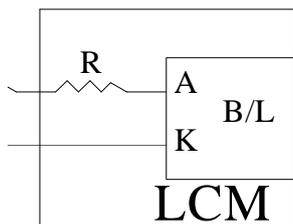
### Specification

PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION
Supply Current	$I_{LED}$	297	330	396	mA	$V=4.1V$
Supply Voltage	V	4.0	4.1	4.3	V	—
Reverse Voltage	$V_R$	—	—	8	V	—
Luminous Intensity (Without LCD)	IV	220	280	—	cd/m <sup>2</sup>	$I_{LED}=330mA$
Wave Length	$\lambda_p$	568	571	573	nm	$I_{LED}=330mA$
Life Time	—	—	100000	—	hr.	$V \leq 4.1V$
Color	Yellow Green					

**Note:**

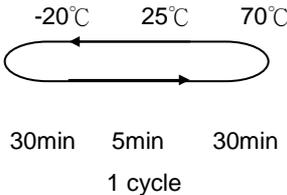
The LED of B/L is drive by current only; drive voltage is for reference only. Drive voltage has to make driving current under safety area.(The current between minimum and maximum)

.Drive from pin19,pin20



## 12. Reliability

### Content of Reliability Test (wide temperature, -20°C~70°C)

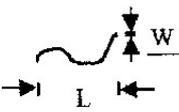
Environmental Test			
Test Item	Content of Test	Condition	Note
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80°C 200hrs	2
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30°C 200hrs	1,2
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 200hrs	-
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1
High Temperature/ Humidity Operation	The module should be allowed to stand at 60°C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°C,90%RH 96hrs	1,2
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation   30min   5min   30min 1 cycle	-20°C/70°C 10 cycles	-
Vibration test	Endurance test applying the vibration during transportation and using.	fixed amplitude: 15mm Vibration. Frequency: 10~55Hz. One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=800V,RS= 1.5kΩ CS=100pF 1 time	—

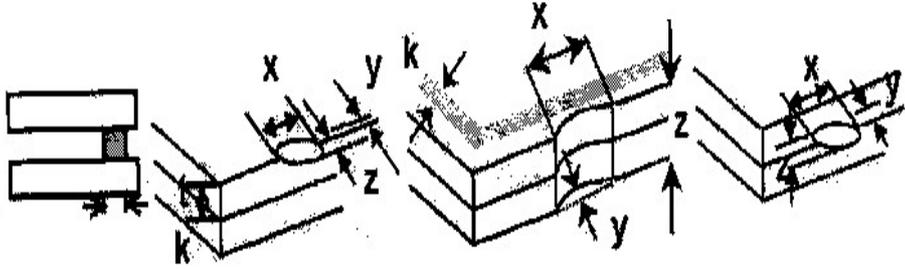
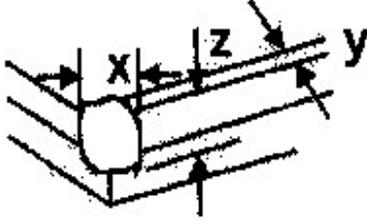
**Note1: No dew condensation to be observed.**

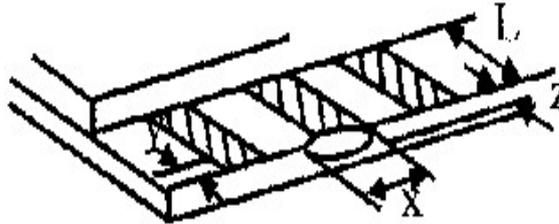
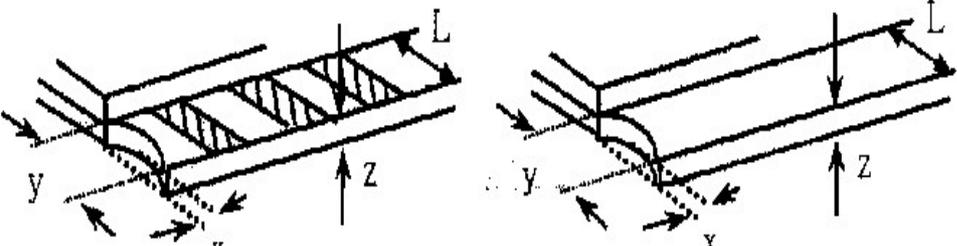
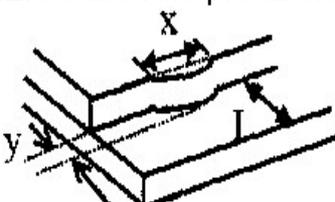
**Note2: The function test shall be conducted after 4 hours storage at the normal temperature and humidity after remove from the test chamber.**

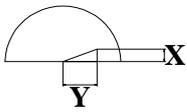
**Note3: The packing have to including into the vibration testing.**

### 13. Inspection specification

NO	Item	Criterion	AQL												
01	Electrical Testing	1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect.	0.65												
02	Black or white spots on LCD (display only)	2.1 White and black spots on display $\leq 0.25\text{mm}$ , no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm	2.5												
03	LCD black spots, white spots, contamination (non-display)	3.1 Round type : As following drawing $\Phi = (x + y) / 2$	2.5												
		3.2 Line type : (As following drawing)  <table border="1" style="margin-left: 20px;"> <thead> <tr> <th>Length</th> <th>Width</th> <th>Acceptable QTY</th> </tr> </thead> <tbody> <tr> <td>---</td> <td><math>W \leq 0.02</math></td> <td>Accept no dense</td> </tr> <tr> <td><math>L \leq 3.0</math></td> <td><math>0.02 &lt; W \leq 0.03</math></td> <td rowspan="2">2</td> </tr> <tr> <td><math>L \leq 2.5</math></td> <td><math>0.03 &lt; W \leq 0.05</math></td> </tr> <tr> <td>---</td> <td><math>0.05 &lt; W</math></td> <td>As round type</td> </tr> </tbody> </table>		Length	Width	Acceptable QTY	---	$W \leq 0.02$	Accept no dense	$L \leq 3.0$	$0.02 < W \leq 0.03$	2	$L \leq 2.5$	$0.03 < W \leq 0.05$	---
Length	Width	Acceptable QTY													
---	$W \leq 0.02$	Accept no dense													
$L \leq 3.0$	$0.02 < W \leq 0.03$	2													
$L \leq 2.5$	$0.03 < W \leq 0.05$														
---	$0.05 < W$	As round type													
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction. <table border="1" style="margin-left: 20px;"> <thead> <tr> <th>Size <math>\Phi</math></th> <th>Acceptable QTY</th> </tr> </thead> <tbody> <tr> <td><math>\Phi \leq 0.20</math></td> <td>Accept no dense</td> </tr> <tr> <td><math>0.20 &lt; \Phi \leq 0.50</math></td> <td>3</td> </tr> <tr> <td><math>0.50 &lt; \Phi \leq 1.00</math></td> <td>2</td> </tr> <tr> <td><math>1.00 &lt; \Phi</math></td> <td>0</td> </tr> <tr> <td>Total QTY</td> <td>3</td> </tr> </tbody> </table>	Size $\Phi$	Acceptable QTY	$\Phi \leq 0.20$	Accept no dense	$0.20 < \Phi \leq 0.50$	3	$0.50 < \Phi \leq 1.00$	2	$1.00 < \Phi$	0	Total QTY	3	2.5
Size $\Phi$	Acceptable QTY														
$\Phi \leq 0.20$	Accept no dense														
$0.20 < \Phi \leq 0.50$	3														
$0.50 < \Phi \leq 1.00$	2														
$1.00 < \Phi$	0														
Total QTY	3														

NO	Item	Criterion	AQL																		
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination																			
06	Chipped glass	<p>Symbols Define:            x: Chip length      y: Chip width      z: Chip thickness            k: Seal width      t: Glass thickness      a: LCD side length            L: Electrode pad length:</p> <p>6.1 General glass chip :            6.1.1 Chip on panel surface and crack between panels:</p>  <table border="1" data-bbox="443 1075 1348 1232"> <thead> <tr> <th>z: Chip thickness</th> <th>y: Chip width</th> <th>x: Chip length</th> </tr> </thead> <tbody> <tr> <td><math>Z \leq 1/2t</math></td> <td>Not over viewing area</td> <td><math>x \leq 1/8a</math></td> </tr> <tr> <td><math>1/2t &lt; z \leq 2t</math></td> <td>Not exceed 1/3k</td> <td><math>x \leq 1/8a</math></td> </tr> </tbody> </table> <p>⊙ If there are 2 or more chips, x is total length of each chip.</p> <p>6.1.2 Corner crack:</p>  <table border="1" data-bbox="443 1612 1348 1769"> <thead> <tr> <th>z: Chip thickness</th> <th>y: Chip width</th> <th>x: Chip length</th> </tr> </thead> <tbody> <tr> <td><math>Z \leq 1/2t</math></td> <td>Not over viewing area</td> <td><math>x \leq 1/8a</math></td> </tr> <tr> <td><math>1/2t &lt; z \leq 2t</math></td> <td>Not exceed 1/3k</td> <td><math>x \leq 1/8a</math></td> </tr> </tbody> </table> <p>⊙ If there are 2 or more chips, x is the total length of each chip.</p>	z: Chip thickness	y: Chip width	x: Chip length	$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$	$1/2t < z \leq 2t$	Not exceed 1/3k	$x \leq 1/8a$	z: Chip thickness	y: Chip width	x: Chip length	$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$	$1/2t < z \leq 2t$	Not exceed 1/3k	$x \leq 1/8a$	2.5
z: Chip thickness	y: Chip width	x: Chip length																			
$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$																			
$1/2t < z \leq 2t$	Not exceed 1/3k	$x \leq 1/8a$																			
z: Chip thickness	y: Chip width	x: Chip length																			
$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$																			
$1/2t < z \leq 2t$	Not exceed 1/3k	$x \leq 1/8a$																			

NO	Item	Criterion	AQL						
06	Glass crack	<p>Symbols :</p> <p>x: Chip length      y: Chip width      z: Chip thickness            k: Seal width      t: Glass thickness      a: LCD side length            L: Electrode pad length</p> <p>6.2 Protrusion over terminal :</p> <p>6.2.1 Chip on electrode pad :</p>  <table border="1" data-bbox="343 900 1257 981"> <thead> <tr> <th>y: Chip width</th> <th>x: Chip length</th> <th>z: Chip thickness</th> </tr> </thead> <tbody> <tr> <td><math>y \leq 0.5\text{mm}</math></td> <td><math>x \leq 1/8a</math></td> <td><math>0 &lt; z \leq t</math></td> </tr> </tbody> </table>	y: Chip width	x: Chip length	z: Chip thickness	$y \leq 0.5\text{mm}$	$x \leq 1/8a$	$0 < z \leq t$	2.5
		y: Chip width	x: Chip length	z: Chip thickness					
		$y \leq 0.5\text{mm}$	$x \leq 1/8a$	$0 < z \leq t$					
		<p>6.2.2 Non-conductive portion:</p>  <table border="1" data-bbox="414 1310 1257 1429"> <thead> <tr> <th>y: Chip width</th> <th>x: Chip length</th> <th>z: Chip thickness</th> </tr> </thead> <tbody> <tr> <td><math>y \leq L</math></td> <td><math>x \leq 1/8a</math></td> <td><math>0 &lt; z \leq t</math></td> </tr> </tbody> </table>	y: Chip width	x: Chip length	z: Chip thickness	$y \leq L$	$x \leq 1/8a$	$0 < z \leq t$	
y: Chip width	x: Chip length	z: Chip thickness							
$y \leq L$	$x \leq 1/8a$	$0 < z \leq t$							
<p>⊙ If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications.</p> <p>⊙ If the product will be heat sealed by the customer, the alignment mark not be damaged.</p>									
<p>6.2.3 Substrate protuberance and internal crack.</p>  <table border="1" data-bbox="750 1675 1260 1758"> <thead> <tr> <th>y: width</th> <th>x: length</th> </tr> </thead> <tbody> <tr> <td><math>y \leq 1/3L</math></td> <td><math>x \leq a</math></td> </tr> </tbody> </table>	y: width	x: length	$y \leq 1/3L$	$x \leq a$					
y: width	x: length								
$y \leq 1/3L$	$x \leq a$								

NO	Item	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
08	Backlight elements	8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong.	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination. 9.2 Bezel must comply with job specifications.	2.5 0.65
10	PCB · COB	10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 10.9 The Scraping testing standard for Copper Coating of PCB  $X * Y \leq 2\text{mm}^2$	2.5 2.5 0.65 2.5 2.5 0.65 0.65 2.5 2.5
11	Soldering	11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB.	2.5 2.5 2.5 0.65

NO	Item	Criterion	AQL
12	General appearance	12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.	2.5
		12.2 No cracks on interface pin (OLB) of TCP.	0.65
		12.3 No contamination, solder residue or solder balls on product.	2.5
		12.4 The IC on the TCP may not be damaged, circuits.	2.5
		12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it causes the interface pin to sever.	2.5
		12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color.	2.5
		12.7 Sealant on top of the ITO circuit has not hardened.	0.65
		12.8 Pin type must match type in specification sheet.	0.65
		12.9 LCD pin loose or missing pins.	0.65
		12.10 Product packaging must the same as specified on packaging specification sheet.	0.65
		12.11 Product dimension and structure must conform to product specification sheet.	0.65

## 14. Precautions in use of LCD Modules

1. Avoid applying excessive shocks to the module or making any alterations or modifications to it.
2. Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
3. Don't disassemble the LCM.
4. Don't operate it above the absolute maximum rating.
5. Don't drop, bend or twist LCM.
6. Soldering: only to the I/O terminals.
7. Storage: please storage in anti-static electricity container and clean environment.
8. Raystar have the right to change the passive components  
(Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
9. Raystar have the right to change the PCB Rev.

## 15. Material List of Components for RoHs

1. RAYSTAR Optronics Co., Ltd. hereby declares that all of or part of products, including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A : The Harmful Material List

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm
Above limited value is set up according to RoHS.						

2. Process for RoHS requirement :

- (1) Use the Sn/Ag/Cu soldering surface ; the surface of Pb-free solder is rougher than we used before.
- (2) Heat-resistance temp. :  
 Reflow : 250°C , 30 seconds Max. ;  
 Connector soldering wave or hand soldering : 320°C , 10 seconds max.
- (3) Temp. curve of reflow, max. Temp. : 235±5°C ;  
 Recommended customer's soldering temp. of connector : 280°C , 3 seconds.

## 16. Recommendable storage

1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
2. Do not place the module near organics solvents or corrosive gases.
3. Do not crush, shake, or jolt the module

**LCM Sample Estimate Feedback Sheet**

Module Number : \_\_\_\_\_

**1 、 Panel Specification :**

1. Panel Type :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
2. View Direction :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
3. Numbers of Dots :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
4. View Area :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
5. Active Area :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
6. Operating Temperature :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
7. Storage Temperature :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
8. Others :	_____	

**2 、 Mechanical Specification :**

1. PCB Size :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
2. Frame Size :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
3. Material of Frame :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
4. Connector Position :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
5. Fix Hole Position :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
6. Backlight Position :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
7. Thickness of PCB :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
8. Height of Frame to PCB :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
9. Height of Module :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
10. Others :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____

**3 、 Relative Hole Size :**

1. Pitch of Connector :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
2. Hole size of Connector :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
3. Mounting Hole size :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
4. Mounting Hole Type :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
5. Others :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____

**4 、 Backlight Specification :**

1. B/L Type :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
2. B/L Color :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
3. B/L Driving Voltage (Reference for LED Type) :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
4. B/L Driving Current :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
5. Brightness of B/L :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
6. B/L Solder Method :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
7. Others :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____

>> Go to page 2 <<

